

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (CANCELED).

2. (CANCELED).

3. (CURRENTLY AMENDED) A base body for a photosensitive drum according to claim ~~1~~ 6, wherein said low water absorption resin is one kind or two or more kinds selected from polypropylene, polyphenylene ether, and polyphenylene sulfide.

4. (CURRENTLY AMENDED) A base body for a photosensitive drum according to claim ~~1~~ 6, wherein said polyamide resin is one kind or two or more kinds selected from polyamide resins including polyamide 11, polyamide 12, polyamide 46, polyamide 6, polyamide 66, polyamide resin produced by polycondensation of metaxylylene diamine and adipic acid, polyamide 610, polyamide 612, polyamide 1212, and copolymers thereof.

5. (CURRENTLY AMENDED) A base body for a photosensitive drum according to claim ~~1~~ 6, wherein a content of said low water absorption resin is in a range of 1 to 70 wt% on the basis of the total weight of said resin base material.

6. (CURRENTLY AMENDED) A base body for a photosensitive drum, wherein said base body has a cylindrical shape and is made of a conductive resin composition; wherein, said resin composition consists essentially of a resin base material and a conductive agent,
wherein said resin base material is a mixed resin of a polyamide resin and a low water absorption resin having a water absorption percentage in a range of 0.3% or less; A base body for a photosensitive drum according to claim 1, and wherein said conductive resin composition further comprises a compatibility enhancing agent for enhancing a compatibility between said polyamide resin and said low water absorption resin.

7. (ORIGINAL) A base body for a photosensitive drum according to claim 6, wherein said compatibility enhancing agent is either or both of maleic acid modified polypropylene and polystyrene-polymethylmethacrylate copolymer.

Claims 8. - 26. (CANCELED).

27. (CURRENTLY AMENDED) A photosensitive drum according to claim-25 30, wherein said low water absorption resin is one kind or two or more kinds selected from polypropylene, polyphenylene ether, and polyphenylene sulfide.

28. (CURRENTLY AMENDED) A photosensitive drum according to claim-~~25~~ 30, wherein said polyamide resin is one kind or two or more kinds selected from polyamide resins including polyamide 11, polyamide 12, polyamide 46, polyamide 6, polyamide 66, polyamide resin produced by polycondensation of metaxylylene diamine and adipic acid, polyamide 610, polyamide 612, polyamide 1212, and copolymers thereof.

29. (CURRENTLY AMENDED) A photosensitive drum according to claim-~~25~~ 30, wherein a content of said low water absorption resin is in a range of 1 to 70 wt% on the basis of the total weight of said resin base material.

30. (CURRENTLY AMENDED) A photosensitive drum comprising:
a cylindrical base body having a cylindrical shape and made of a conductive resin
composition; and
a photosensitive layer formed on an outer peripheral surface of said cylindrical base
body;
wherein said resin composition consists essentially of a base resin and a conductive
agent, and said resin base material is a mixed resin of a polyamide resin and a low water
absorption resin having a water absorption percentage in a range of 0.3% or less; and
~~A photosensitive drum according to claim 25,~~ wherein said conductive resin composition further comprises a compatibility enhancing agent for enhancing a compatibility between said polyamide resin and said low water absorption resin.

31. (ORIGINAL) A photosensitive drum according to claim 30, wherein said compatibility enhancing agent is either or both of maleic acid modified polypropylene and polystyrene-polymethylmethacrylate polymer.

Claims 32. through 50 (CANCELED).